# DESCRIPTION

~~WORKPIECE MACHINING DEVICE AND WORKPIECE MACHINING METHOD~~

## TECHNICAL FIELD

[0001]

The present invention relates to a method and an apparatus that prevent a fracture in a workpiece by detecting that a workpiece is not properly put in a holding hole of a carrier prior to processing in processing of a workpiece by which the workpiece is held in the holding hole of the carrier and both surfaces of the workpiece are processed at the same time.

## BACKGROUND ART

[0002]

In the past, when, for example, a thin plate-like workpiece such as a silicon wafer is flattened, a double-side polishing apparatus or a double-side lapping apparatus has been used. For example, the double-side polishing apparatus has a disk-shaped carrier with a planet gear at the outer edge thereof between upper and lower turn tables to which a polishing pad formed of urethane foam or a nonwoven fabric is attached. By holding a workpiece in a holding hole of this carrier and mutually rotating a sun gear and an internal gear which engage the planet gear, the rotation and orbital motion of the carrier are generated. By this rotation and orbital motion and the rotation of the upper and lower turn tables and the sliding motion of the upper and lower turn tables and the workpiece, the upper and lower surfaces of the workpiece are polished at the same time. During polishing, in order to perform polishing efficiently, polishing slurry is supplied from a plurality of holes provided in the upper turn table.

[0003]

DESCRIPTION

# WORKPIECE PROCESSING APPARATUS AND WORKPIECE PROCESSING METHOD

## TECHNICAL FIELD

[0001]

The present invention relates to a method and an apparatus that prevent a fracture in a workpiece by detecting that a workpiece is not properly put in a holding hole of a carrier prior to processing in processing of a workpiece by which the workpiece is held in the holding hole of the carrier and both surfaces of the workpiece are processed at the same time.

## BACKGROUND ART

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[0003]